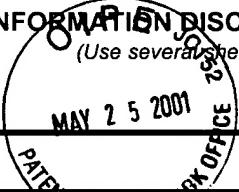
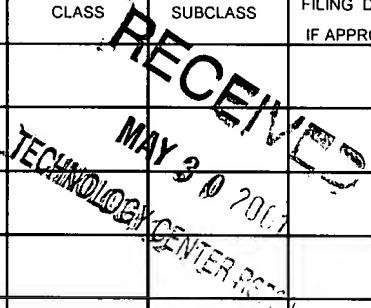


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INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)				ATTY DOCKET NO.	SERIAL NO.	
				McCarte	09/778,525	
 MAY 25 2001				Douglas Ronald McCarter et al. FILING 02/06/01 GROUP		
U. S. PATENT DOCUMENTS						
*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
 MAY 30 2001						
FOREIGN PATENT DOCUMENTS						
	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION
						YES
						NO
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)						
GN	AE	S. Danyluk, et al.: "Influence of Fluids on the Abrasion of Silicon By Diamond", University of Illinois at Chicago Circle, 20 pages.				
GN	AF	M.J. Ball, et al.: "Cost Effective Edge Machining of Silicon Wafers to Minimize The Polishing Process", 1998 Spring Tropical Meeting Volume 17, pp. 50, 51, 53 plus 3 pages.				
EXAMINER			DATE CONSIDERED 4/11/02			

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